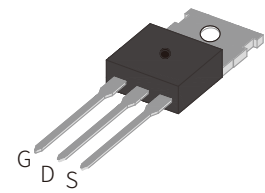
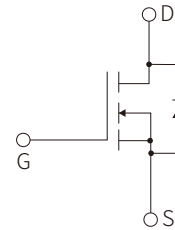


FEATURES

- | Low Gate Charge
- | Low Crss
- | Fast Switching
- | Improved dv/dt and ESD Capability
- | 100% Avalanche energy test



TO-220C



Schematic Symbol

APPLICATION

- | High Frequency Switched-Mode Power Supply
- | Electronic lamp ballasts
- | UPS

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

ABSOLUTE MAXIMUM RATINGS ($T_A=25^{\circ}\text{C}$)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	800	V
Continuous Drain Current	$T_C=25^{\circ}\text{C}$	I_D	12*	A
	$T_C=100^{\circ}\text{C}$		6*	A
Pulsed Drain Current (note1)		I_{DM}	36	A
Gate-Source Voltage		V_{GS}	± 30	V
Avalanche Current (note1)		I_{AR}	12	A
Repetitive Avalanche Energy (note1)		E_{AR}	20	mJ
Single Pulsed Avalanche Energy (note2)		E_{AS}	225	mJ
Peak Diode Recovery (note3)		dv/dt	4.5	V/ns
Power Dissipation $T_C=25^{\circ}\text{C}$		P_D	140	W
Power Dissipation Derating Factor Above 25°C		$P_{D(DF)}$	1.12	W/ $^{\circ}\text{C}$
Maximum Temperature for Soldering		T_L	300	$^{\circ}\text{C}$
Operating Junction Temperature Range		T_J	150	$^{\circ}\text{C}$
Storage Temperature Range		T_{STG}	-55 to +150	$^{\circ}\text{C}$
Thermal Resistance, Junction to Case		$R_{th(j-c)}$	0.89	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction to Ambient		$R_{th(j-a)}$	62.5	$^{\circ}\text{C}/\text{W}$

* Drain current limited by maximum junction temperature

ELECTRICAL CHARACTERISTICS (T_A=25°C)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	800			V
Breakdown Voltage Temperature Coefficient	ΔBV _{DSS} / ΔT _J	I _D =250uA, referenced to 25°C		0.7		V/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =800V, V _{GS} =0V, T _C =25°C			1	μA
		V _{DS} =640V, T _C =125°C			100	μA
Gate Leakage Current	I _{GSS}	V _{GS} =30V, V _{DS} =0V			100	nA
		V _{GS} =-30V, V _{DS} =0V			-100	nA
On Characteristics						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2.0		4.0	V
Drain-source On-resistance	R _{DS(on)}	V _{GS} =10V, I _D =6A		0.6	0.8	Ω
Forward Transconductance	g _{FS}	V _{DS} =40V, I _D =6A (note 4)		5.7		S
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} = 25V, V _{GS} = 0V, f=1.0MHz		2100		pF
Output Capacitance	C _{oss}			225		pF
Reverse Transfer Capacitance	C _{rss}			32		pF
Turn-On Delay Time	t _{d(on)}	V _{DD} =400V, I _D =12A, R _G =25Ω (note 4,5)		38		ns
Turn-On Rise Time	t _r			105		ns
Turn-Off Delay Time	t _{d(off)}			55		ns
Turn-Off Fall Time	t _f			65		ns
Total Gate Charge	Q _g	V _{DS} =640V, I _D =12A, V _{GS} =10V (note 4,5)		34		nC
Gate-Source Charge	Q _{gs}			8.7		nC
Gate-Drain Charge	Q _{gd}			13		nC
Maximum Continuous Drain-Source Diode Forward Current	I _S				12	A
Maximum Pulsed Drain-Source Diode Forward Current	I _{SM}				36	A
Drain-Source Diode Forward Voltage	V _{SD}	I _S =12A, V _{GS} =0V			1.4	V
Reverse Recovery Time	t _{rr}	I _S =12A, V _{GS} =0V, dI _F /dt=100A/μs(note 4)		650		ns
Reverse Recovery Charge	Q _{rr}			7.0		μC

Notes:

1: Pulse width limited by maximum junction temperature
 3: I_{SD} ≤ 12A, di/dt ≤ 300A/μs, V_{DD} ≤ BV_{DSS}, Starting T_J=25°C
 5: Essentially independent of operating temperature

2: L=0.5mH, I_{AS}=30A, V_{DD}=50V, R_G=25Ω, Starting T_J=25°C
 4: Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%

CHARACTERISTIC CURVES

Fig.1 On-State Characteristics

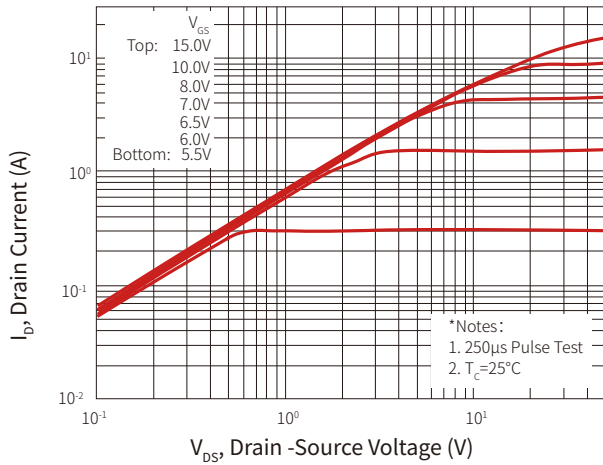


Fig.2 Transfer Characteristics

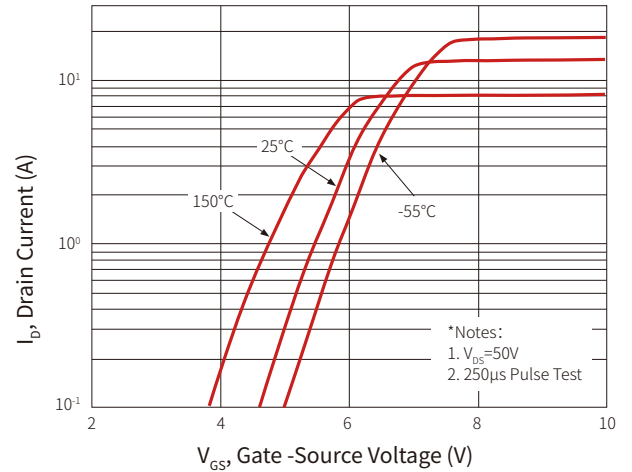


Fig.3 Capacitance Characteristics

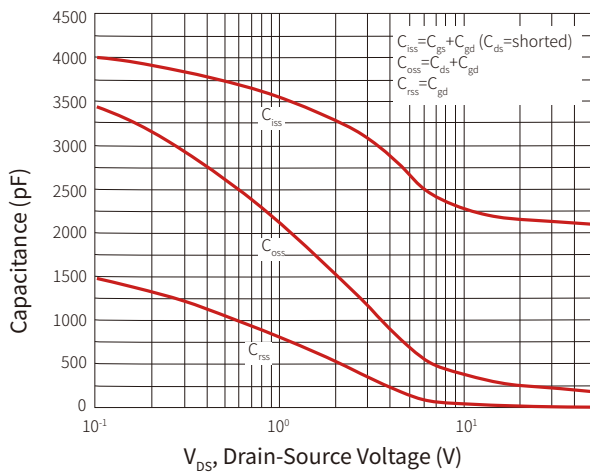


Fig. 4 Gate Charge Characteristics

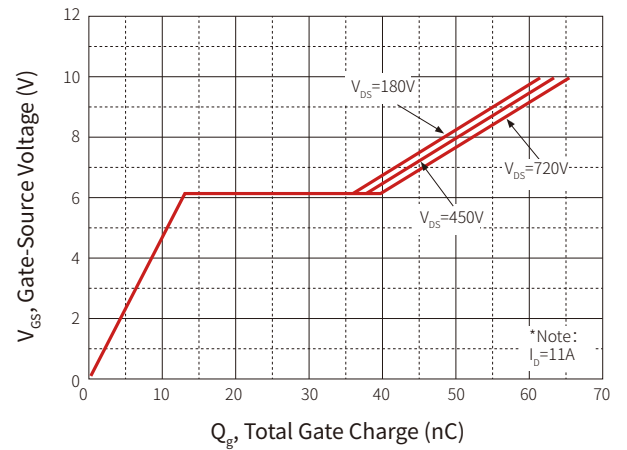


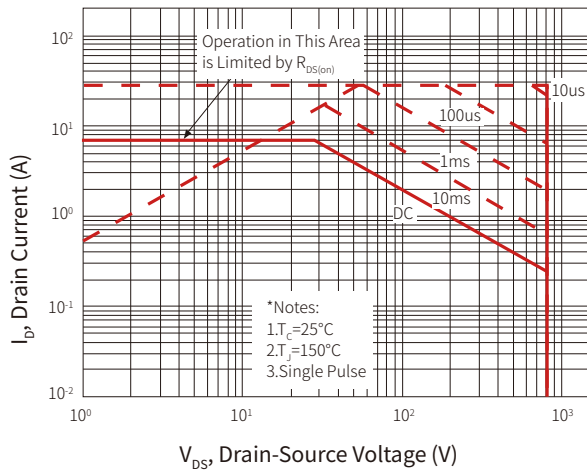
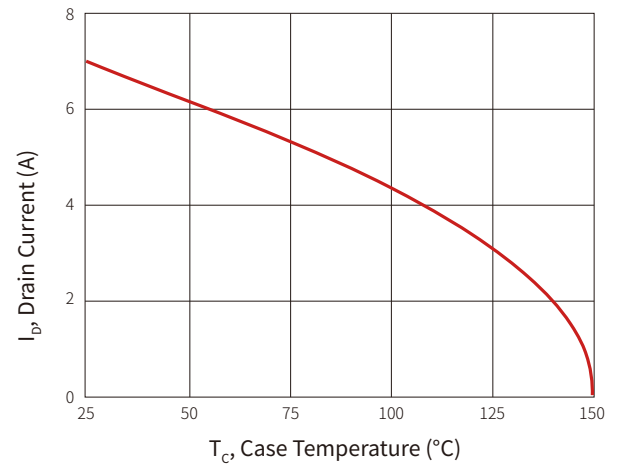
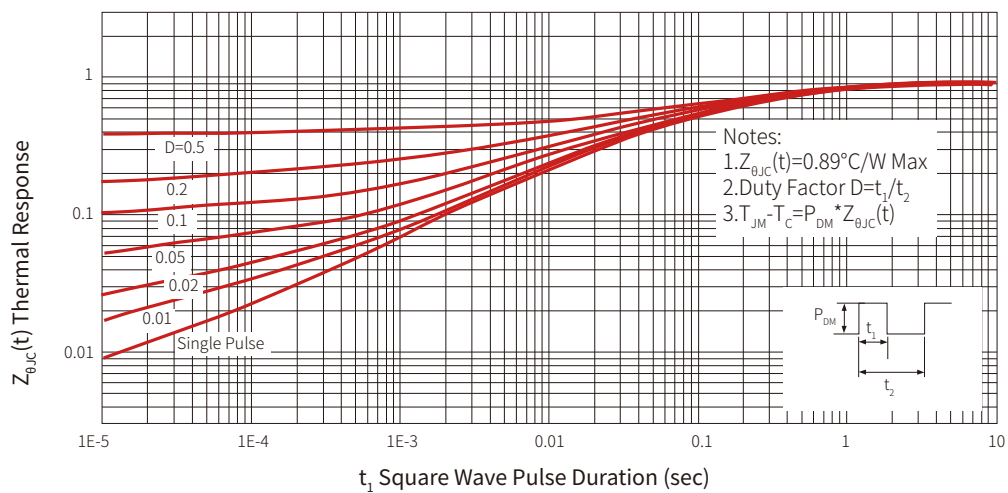
Fig.5 Maximum Safe Operating Area

Fig.6 Maximum Drain Current vs Case Temperature

Fig.7 Transient Thermal Response Curve


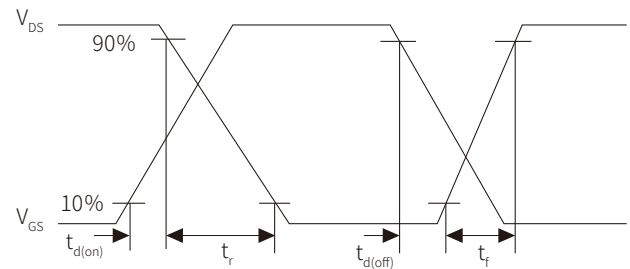
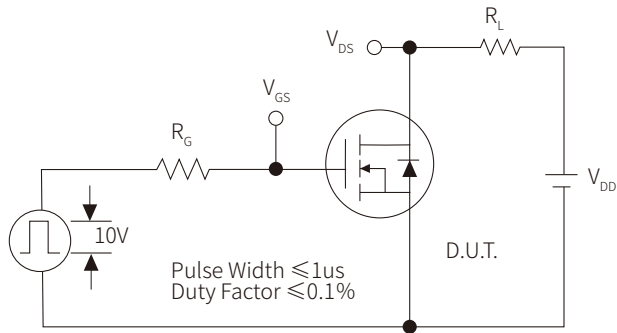
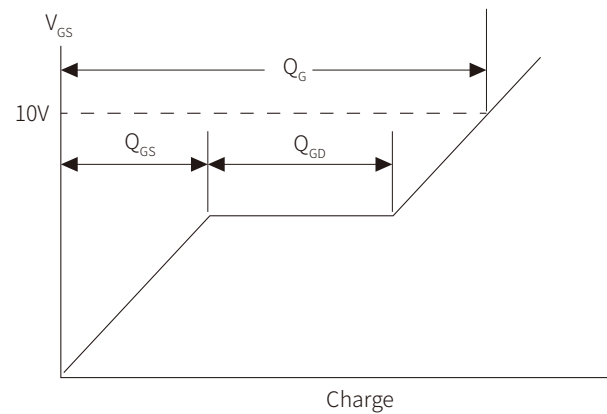
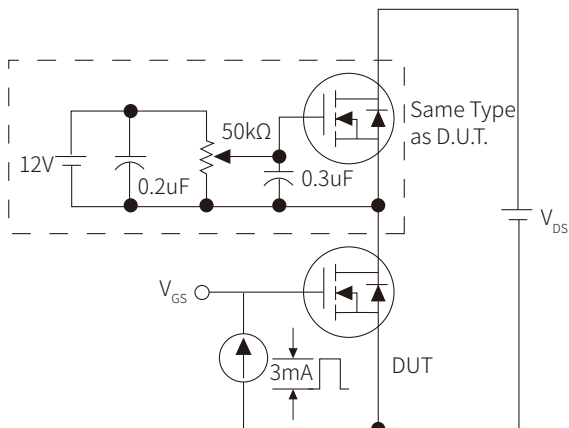
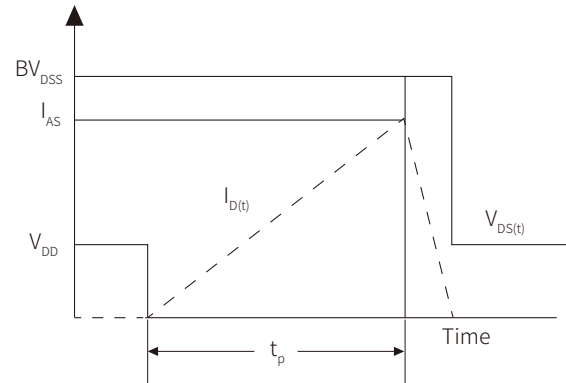
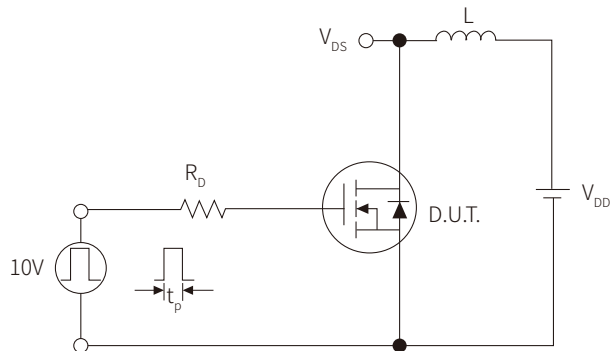
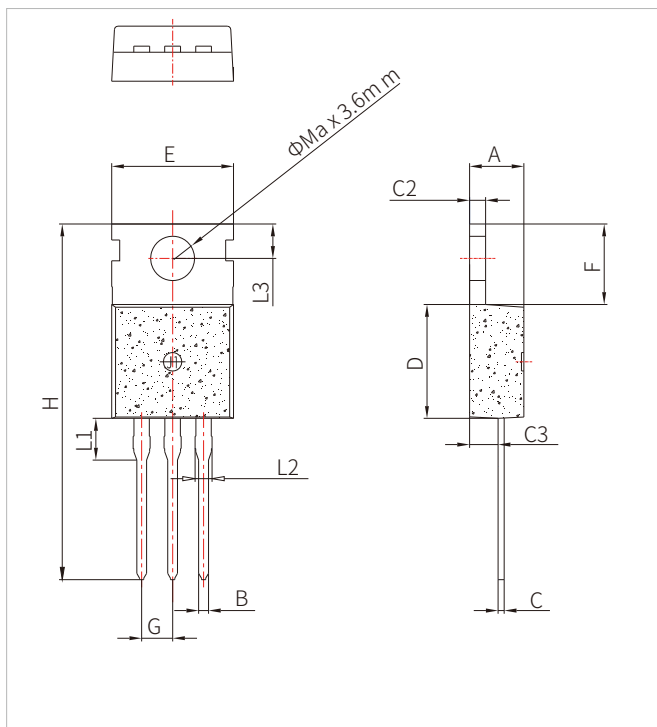
Fig.8 Resistive Switching Test Circuit & Waveforms

Fig.9 Gate Charge Test Circuit & Waveform


Fig.10 Unclamped Inductive Switching Test Circuit & Waveforms


TO-220C PACKAGE MECHANICAL DATA



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.30		4.70	0.169		0.185
B	0.70		0.90	0.028		0.035
C	0.45		0.60	0.018		0.024
C2	1.23		1.32	0.048		0.052
C3	2.20		2.60	0.087		0.102
D	8.80		10.0	0.346		0.394
E	9.90		10.3	0.390		0.406
F	6.30		6.90	0.248		0.272
G		2.54			0.1	
H	28.0		30.0	1.102		1.181
L1		3.65			0.144	
L2	1.14		1.70	0.045		0.067
L3	2.65		2.95	0.104		0.116
Φ		3.6			0.142	

ORDERING INFORMATION

Part Number	Package	Marking	Qty/pcs		
			Tube	Inner Box	Carton
SNM12N80C	TO-220C	 12N80 XXXX	50	1000	5000

Headquarters

No.3387 Shendu Road
Pujiang I&E Park
Minhang Shanghai China
201000

Hotline

400-021-5756

Web

<https://www.semiware.com>

Sales Center

Tel: 86-21-3463-7458
Email: sales18@semiware.com

Customer Service

Tel: 86-21-5484-1001
Email: sales17@semiware.com

Technical Support

Tel: 86-21-3463-7654
Email: fae01@semiware.com

Complaint & Suggestions

Tel: 86-21-3463-7172
Ext: 8868
Email: cs03@semiware.com

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